

IN THE CLAIMS

Please amend the claims as follows:

1. (Currently Amended) An imaging device including integrally an imaging element to be mounted on a substrate and an optical element having an imaging lens section for providing a light-receiving surface of the imaging element with optical information, wherein the substrate has an opening section;
the imaging element is fastened on the substrate so as to close the opening section with a surface including the light-receiving surface; and
the optical element is in direct contact with the upper surface of the imaging element by way of the opening section.
2. (Original) The imaging device according to claim 1, wherein connection means for establishing electrical connection between the substrate and the imaging element is provided in an overlap between the substrate and the imaging element; and the optical element is in contact with areas on the upper surface of the imaging element other than the light-receiving surface.
3. (Withdrawn) The imaging device according to claim 1, wherein the optical element remaining in contact with the upper surface of the imaging element by way of the opening section is bonded to the substrate by means of an adhesive.
4. (Withdrawn) The imaging device according to claim 3, wherein an adhesive used for bonding the optical element to the substrate is a thermoplastic-resin-based adhesive.
5. (Withdrawn) The imaging device according to claim 1, wherein a contact area where the optical element is in contact with the imaging element surrounds the overall

periphery of the light-receiving surface.

6. (Withdrawn) The imaging device according to claim 1, further comprising imaging element sealing resin which is arranged so as to close a boundary between the periphery of the imaging element and the substrate and which exhibits an adhesive strength improvement function, a moisture-absorption prevention function, an extraneous material entry prevention function, and a light-shielding function.

7. (Withdrawn) The imaging device according to claim 1, further comprising optical element sealing resin which covers the optical element remaining in contact with the upper surface of the imaging element, thereby integrating the optical element with the substrate, and which has an extraneous material entry prevention function, a moisture-absorption prevention function, and a shock dampening function.

8. (Withdrawn) The imaging device according to claim 7, wherein the optical element sealing resin has a light-shielding function.

9.-18. (Canceled)

19. (Currently Amended) An imaging device comprising:

a substrate having an opening section;

an imaging element mounted on the substrate, the imaging element having a light receiving surface; and

an optical element having an imaging lens section,

wherein the imaging element is fastened on the substrate so as to close the opening section with a surface including the light-receiving surface, and

the optical element is mounted directly on an upper surface of the imaging element by

way of the opening section.

20. (Previously Presented) The imaging device according to claim 19, wherein connection means for establishing electrical connection between the substrate and the imaging element is provided in an overlap between the substrate and the imaging element; and the optical element is in contact with areas on the upper surface of the imaging element other than the light-receiving surface.

21. (Withdrawn) The imaging device according to claim 19, wherein the optical element remaining in contact with the upper surface of the imaging element by way of the opening section is bonded to the substrate by means of an adhesive.

22. (Withdrawn) The imaging device according to claim 21, wherein an adhesive used for bonding the optical element to the substrate is a thermoplastic-resin-based adhesive.

23. (Withdrawn) The imaging device according to claim 19, wherein a contact area where the optical element is in contact with the imaging element surrounds the overall periphery of the light-receiving surface.

24. (Withdrawn) The imaging device according to claim 19, further comprising imaging element sealing resin which is arranged so as to close a boundary between the periphery of the imaging element and the substrate and which exhibits an adhesive strength improvement function, a moisture-absorption prevention function, an extraneous material entry prevention function, and a light-shielding function.

25. (Withdrawn) The imaging device according to claim 19, further comprising optical element sealing resin which covers the optical element remaining in contact with the upper surface of the imaging element, thereby integrating the optical element with the

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substrate, and which has an extraneous material entry prevention function, a moisture-absorption prevention function, and a shock dampening function.

26. (Withdrawn) The imaging device according to claim 25, wherein the optical element sealing resin has a light-shielding function.